AMENDMENTS

In the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (currently amended) A socket or adapter-device adapted for carrying a semiconductor device to be tested, the test socket or adapter device comprising at least one connection pin, wherein the connection pin extends from a lower surface of the socket or adapter device in a downward direction, the connection pin being configured to be connected to a corresponding contact device~~,~~

~~wherein the connection pin is configured to be connected to the contact device~~ by solderless surface mounting, and the end section of the connection pin has a shape bent back in an upward direction.

2. (original) The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that it can be loaded with a corresponding semiconductor device.

3. (original) The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is configured for performing a burn-in test and can be loaded with a corresponding semiconductor device.

4. (original) The socket or adapter device according to claim 1, wherein the connection pin is made of a flexible or resilient material.

5. (original) The socket or adapter device according to claim 4, wherein the metal alloy includes copper and/or beryllium.

6. (original) The socket or adapter device according to claim 1, wherein at least one section of the connection pin has an arcuate or bent shape.

7. (original) The socket or adapter device according to claim 1, wherein the device comprising the contact device is a circuit board configured to be connected to a testing apparatus.

8. (original) The socket or adapter device according to claim 1, wherein the device comprising the contact device is a testing apparatus.

9. (currently amended) A system, comprising:

at least one socket or adapter device; and

at least one semiconductor device testing apparatus or at least one circuit board, wherein

the socket or adapter device comprises at least one connection pin which is configured to be connected to a corresponding contact device for connection to the testing apparatus or to the circuit board that can be connected with a testing apparatus, and

wherein the connection pin extends from a lower surface of the socket or adapter device in a downward direction, the end section of the connection pin has a shape bent back in an upward direction and the connection pin is connected to the contact device by surface mounting.

10. (original) The system according to claim 9, wherein the connection pin is connected to the contact device without soldering.

11. (original) The system according to claim 9, wherein a device is provided such that the connection pin is pressed against the contact device.

12. (original) The system according to claim 11, wherein the device is an appropriate screw connection.

13. (original) The system according to claim 11, wherein the device is an appropriate clamping connection.

14. (original) The system according to claim 10, wherein the socket or adapter device comprises a plurality of connection pins, each being connected to corresponding contact device, and wherein the conneciton pins each are connected to the respectively corresponding contact devices without soldering.

15. (currently amended) A method for testing semiconductor devices, comprising:

connecting a socket or adapter device to a testing system, wherein at least one connection pin is connected to a corresponding contact device;

loading the socket or adapter device with a semiconductor device to be tested,

wherein the connection pin extends from a lower surface of the socket or adapter device in a downward direction, the end section of the connection pin has a shape bent back in an upward direction and the conneciton of the connection pin too the contact device is perforned by solderless surface mounting.